

# QEE122, QEE123 Plastic Infrared Light Emitting Diode

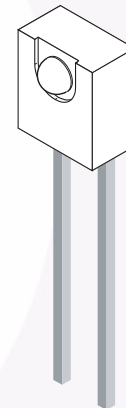
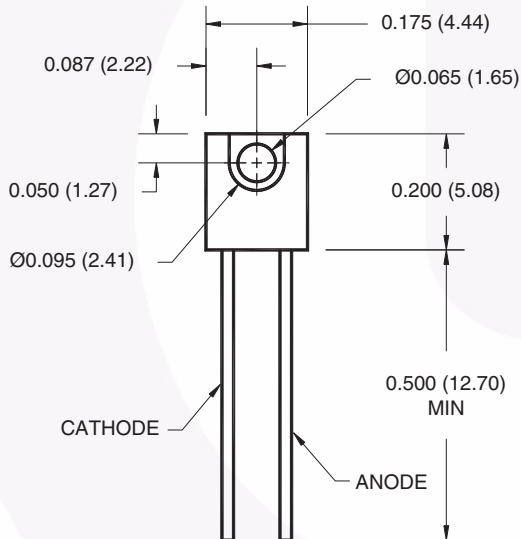
## Features

- $\lambda = 880 \text{ nm}$
- Package Type = Sidelooker
- Chip Material = AlGaAs
- Matched Photosensor: QSE113
- Medium Wide Emission Angle,  $50^\circ$
- Package Material: Clear Epoxy
- High Output Power
- Orange stripe on the top side

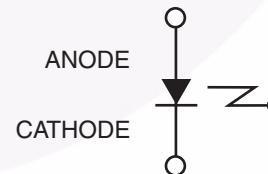
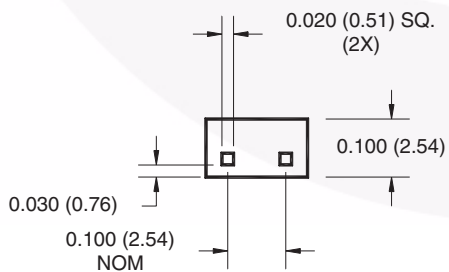
## Description

The QEE12X is a 880 nm AlGaAs LED encapsulated in a medium wide angle, plastic sidelooker package.

## Package Dimensions



## Schematic



### Notes:

1. Dimensions of all drawings are in inches (mm).
2. Tolerance is  $\pm 0.010$  (0.25) on all non-nominal dimensions unless otherwise specified.

**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating	Units
$T_{\text{OPR}}$	Operating Temperature	-40 to +100	$^\circ\text{C}$
$T_{\text{STG}}$	Storage Temperature	-40 to +100	$^\circ\text{C}$
$T_{\text{SOL-I}}$	Soldering Temperature (Iron) <sup>(2)(3)(4)</sup>	240 for 5 sec	$^\circ\text{C}$
$T_{\text{SOL-F}}$	Soldering Temperature (Flow) <sup>(2)(3)</sup>	260 for 10 sec	$^\circ\text{C}$
$I_F$	Continuous Forward Current	100	mA
$V_R$	Reverse Voltage	5	V
$P_D$	Power Dissipation <sup>(1)</sup>	100	mW

**Notes:**

- Derate power dissipation linearly 2.67mW/ $^\circ\text{C}$  above 25 $^\circ\text{C}$ .
- RMA flux is recommended.
- Methanol or isopropyl alcohols are recommended as cleaning agents.
- Soldering iron 1/16" (1.6mm) minimum from housing.

**Electrical / Optical Characteristics** ( $T_A = 25^\circ\text{C}$ )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\lambda_{\text{PE}}$	Peak Emission Wavelength	$I_F = 20\text{mA}$		890		nm
$\text{TC}_\lambda$	Temperature Coefficient			0.2		nm/ $^\circ\text{C}$
$2\theta^{1/2}$	Emission Angle	$I_F = 100\text{mA}$		50		$^\circ$
$V_F$	Forward Voltage	$I_F = 100\text{mA}$ , $t_p = 20\text{ms}$			1.7	V
$\text{TC}_{V_F}$	Temperature Coefficient			-6		mV/ $^\circ\text{C}$
$I_R$	Reverse Current	$V_R = 5\text{V}$			10	$\mu\text{A}$
$I_E$	Radiant Intensity QEE122	$I_F = 100\text{mA}$ , $t_p = 20\text{ms}$	4	9	16	mW/sr
	Radiant Intensity QEE123		8	9		
$\text{TC}_{I_E}$	Temperature Coefficient			-0.3		%/ $^\circ\text{C}$
$t_r$	Rise Time	$I_F = 100\text{mA}$		900		ns
$t_f$	Fall Time			800		ns
$C_j$	Junction Capacitance	$V_R = 0\text{V}$		11		pF

## Typical Performance Curves

Figure 1. Normalized Intensity vs. Wavelength

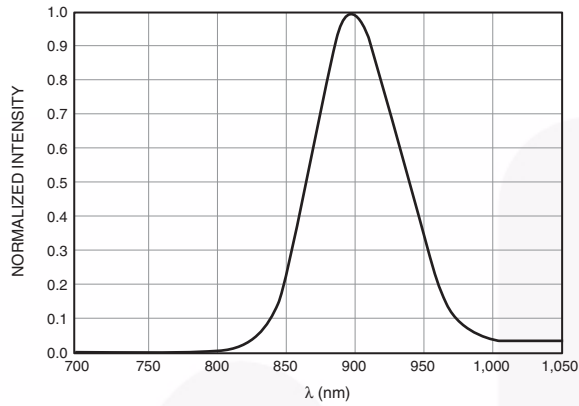


Figure 2. Peak Wavelength vs. Ambient Temperature

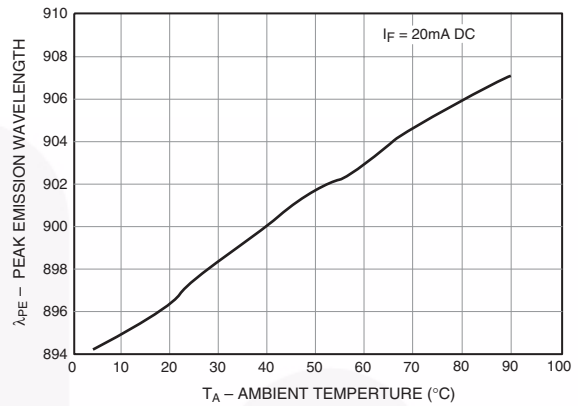


Figure 3. Normalized Radiant Intensity vs. Forward Current

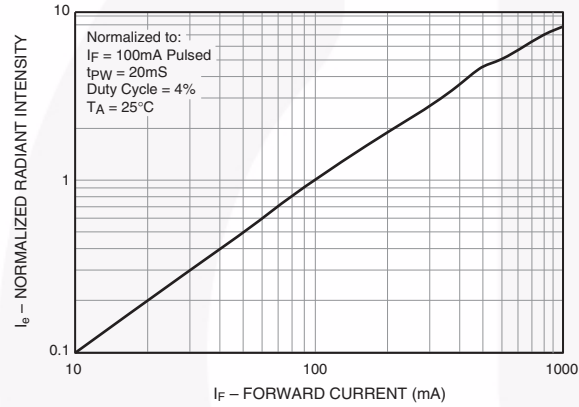


Figure 4. Normalized Radiant Intensity vs. Ambient Temperature

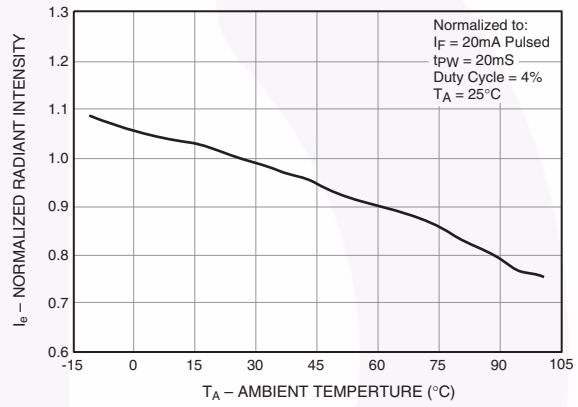


Figure 5. Forward Voltage vs. Forward Current

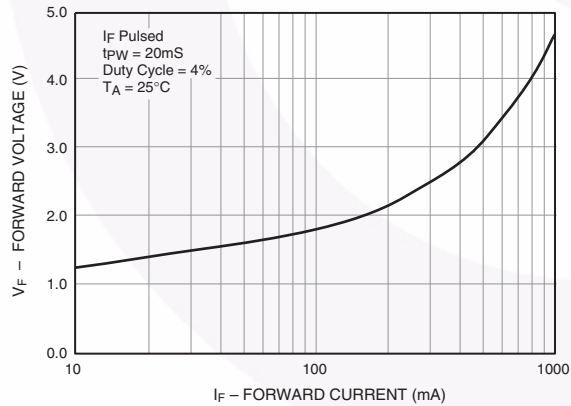
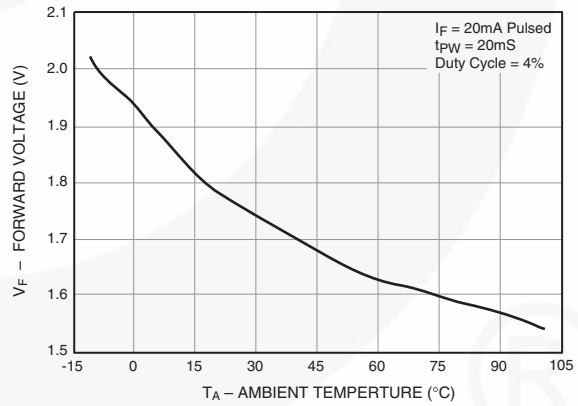


Figure 6. Forward Voltage vs. Ambient Temperature



Typical Performance Curves (Continued)

Figure 7. Radiation Diagram

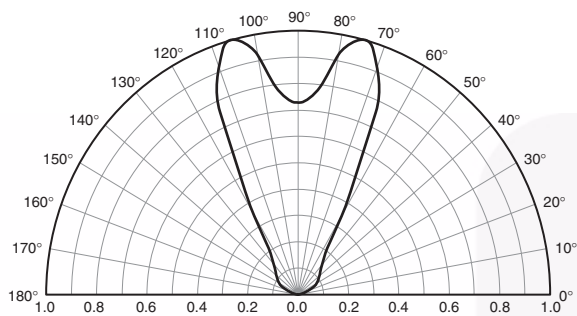
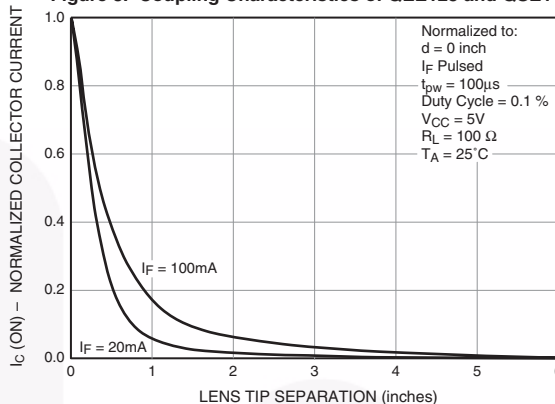








Figure 8. Coupling Characteristics of QEE123 and QSE113





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